L Number	Hits	Search Text	DB	Time stamp
1	1	reinforced adj semiconductor adj	USPAT;	2003/11/15 11:38
		interconnect adj structure	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
2	3	reinforced adj interconnect adj structure	USPAT;	2003/11/15 11:40
-	٦	reinforced day interconnect day beraccure	US-PGPUB;	2003/11/13 11:40
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	15	reinforced adj interconnect	USPAT;	2003/11/15 11:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
4	72	reinforced adj via	USPAT;	2003/11/15 11:43
4	12	reinforced adj via	US-PGPUB;	2003/11/13 11.43
		•	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	56	reinforced adj plug	USPAT;	2003/11/15 11:44
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
6	7	reinforced adj semiconductor adj (device	IBM_TDB USPAT;	2003/11/15 11:45
6	·	or structure or portion or element)	US-PGPUB;	2003/11/13 11.45
		of structure of portion of element,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	39	reinforced adj semiconductor	USPAT;	2003/11/15 11:46
			US-PGPUB;	
			EPO; JPO;	
-			DERWENT;	
0	638	iconductor odi gupporta	IBM_TDB USPAT;	2003/11/15 11:46
8	638	semiconductor adj supports	US-PGPUB;	2003/11/13 11.40
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	73	semiconductor adj support adj structures	USPAT;	2003/11/15 11:48
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
10	9	 semiconductor adj support adj elements	USPAT;	2003/11/15 11:49
10]	Semisonadotor daj support daj erements	US-PGPUB;	
	1		EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
11	7	semiconductor adj support adj (region or	USPAT;	2003/11/15 11:49
		area or potion)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
12	11	 semiconductor adj support adj (region or	USPAT;	2003/11/15 11:51
		area or portion)	US-PGPUB;	
		•	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/11/15 10 5
13	150	(multilevel adj metallization) and	USPAT;	2003/11/15 12:00
		(supports or reinforcements)	US-PGPUB; EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
14	56	 (plurality adj metallization) and	USPAT;	2003/11/15 12:10
1 3		(supports or reinforcements)	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	

15	202	(plurality adj metal adj (layers or	USPAT;	2003/11/15 12:13
15	202	films)) and (supports or reinforcements)	US-PGPUB;	2000, 11, 10 12.10
		lilmo,, and (bappoles of realizations,	EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	45	(first adj metal adj interconnect) and	USPAT;	2003/11/15 12:16
10		(supports or reinforcements)	US-PGPUB;	
		(our contraction of the contract	EPO; JPO;	
			DERWENT;	
			IBM TDB	
17	283	first adj metal adj interconnect	USPAT;	2003/11/15 12:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
18	62	plurality adj metal adj interconnect	USPĀT;	2003/11/15 12:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
19	36	multiple adj metal adj interconnect	USPAT;	2003/11/15 12:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
20	87	multilevel adj metal adj interconnect	USPAT;	2003/11/15 12:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	